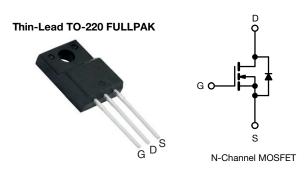
Vishay Siliconix

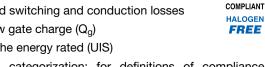
E Series Power MOSFET



PRODUCT SUMMARY			
V _{DS} (V) at T _J max.	85	50	
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V 1.1		
Q _g max. (nC)	3	2	
Q _{gs} (nC)	Q_{gs} (nC) 4		
Q _{gd} (nC)	(6	
Configuration	Sin	gle	

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
- Induction heating
- Motor drives
- Battery chargers
- Renewable energy
- Solar (PV inverters)

ORDERING INFORMATION	
Package	Thin-lead TO-220 FULLPAK
Lead (Pb)-free and halogen-free	SiHA4N80E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	800	V
Gate-source voltage	V _{GS} ± 30		v		
O-ation - during - 150 00\ 8	V -+ 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$,	4.3	
Continuous drain current (T _J = 150 °C) ^e	V _{GS} at 10 V	T _C = 100 °C	I _D	2.7	Α
Pulsed drain current ^a			I _{DM}	11	
Linear derating factor				0.24	W/°C
Single pulse avalanche energy b			E _{AS}	56	mJ
Maximum power dissipation			P_{D}	69	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope	T _J = 125 °C		dv./dt	70	V/ns
Reverse diode dv/dt ^d			dv/dt	0.3	V/IIS
Soldering recommendations (peak temperature) ^c	For	10 s		300	°C
Mounting torque	M3 s	screw		0.6	Nm

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature b. $V_{DD}=140~V,$ starting $T_J=25~^\circ C,~L=28.2~mH,~R_g=25~\Omega,~I_{AS}=2.0~A$
- 1.6 mm from case

S17-1345-Rev. A, 04-Sep-17

- $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting $T_J = 25$ °C
- Limited by maximum junction temperature



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R_{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	4.1	C/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		800	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	1.1	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Out on the last	,		$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
		V _{DS} =	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 640 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 2 A	-	1.1	1.27	Ω
Forward transconductance	9 _{fs}	V _{DS}	s = 30 V, I _D = 2 A	-	1.5	-	S
Dynamic					•		•
Input capacitance	C _{iss}	$V_{GS} = 0 V$,		-	622	-	pF
Output capacitance	C _{oss}		V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		34	-	
Reverse transfer capacitance	C _{rss}				5	-	
Effective output capacitance, energy related ^a	C _{o(er)}			-	21	-	
Effective output capacitance, time related ^b	$C_{o(tr)}$	$V_{DS} = 0$	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$		91	-	
Total gate charge	Qg			-	16	32	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$I_D = 2 A, V_{DS} = 480 V$	-	4	-	nC
Gate-drain charge	Q _{gd}			-	6	-	
Turn-on delay time	t _{d(on)}	'		-	12	24	1
Rise time	t _r	Van	V_{DD} = 480 V, I_{D} = 2 A, V_{GS} = 10 V, R_{g} = 9.1 Ω		7	14	
Turn-off delay time	t _{d(off)}				26	52	ns
Fall time	t _f				20	40	1
Gate input resistance	R_g	f = 1	f = 1 MHz, open drain		1.2	2.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	4.4	
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	11	A
Diode forward voltage	V _{SD}	T _J = 25 °	°C, I _S = 2 A, V _{GS} = 0 V	-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 2 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	248	496	ns
Reverse recovery charge	Q _{rr}			-	1.4	2.8	μC
Reverse recovery current	I _{RRM}			_	9.2	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS}

b. Coss(tr) is a fixed capacitance that gives the same charging time as Coss while VDS is rising from 0 V to 480 V VDSS



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

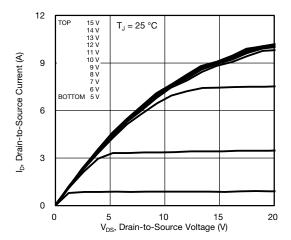


Fig. 1 - Typical Output Characteristics

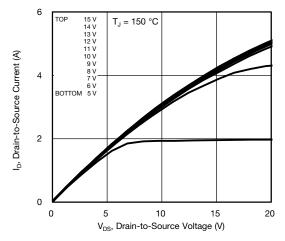


Fig. 2 - Typical Output Characteristics

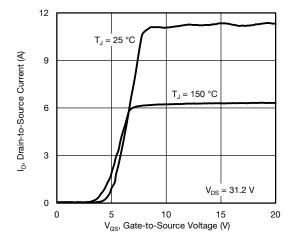


Fig. 3 - Typical Transfer Characteristics

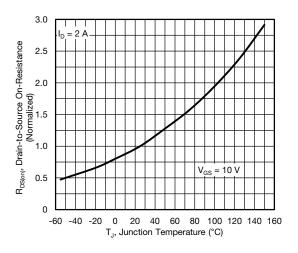


Fig. 4 - Normalized On-Resistance vs. Temperature

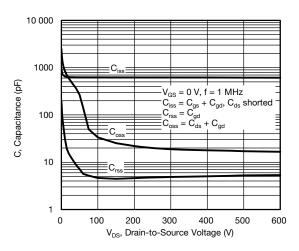


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

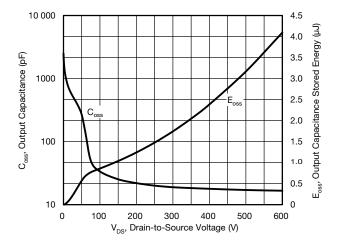


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



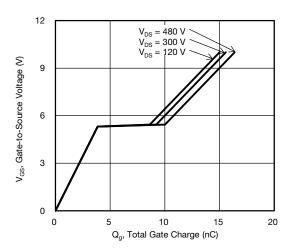


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

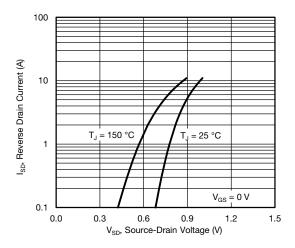


Fig. 8 - Typical Source-Drain Diode Forward Voltage

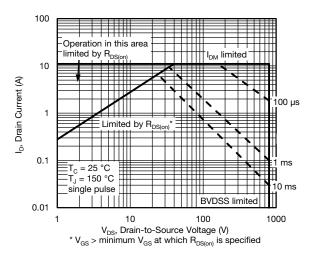


Fig. 9 - Maximum Safe Operating Area

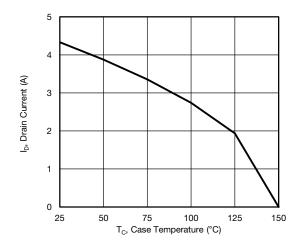


Fig. 10 - Maximum Drain Current vs. Case Temperature

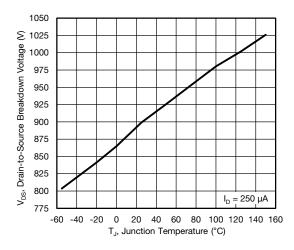


Fig. 11 - Temperature vs. Drain-to-Source Voltage



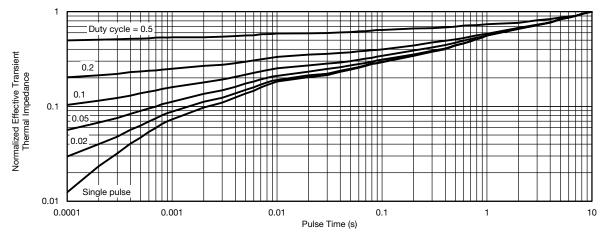


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

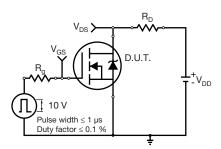


Fig. 13 - Switching Time Test Circuit

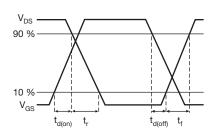


Fig. 14 - Switching Time Waveforms

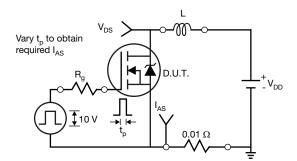


Fig. 15 - Unclamped Inductive Test Circuit

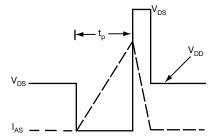


Fig. 16 - Unclamped Inductive Waveforms

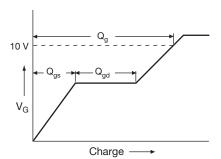


Fig. 17 - Basic Gate Charge Waveform

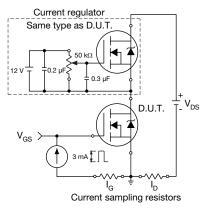
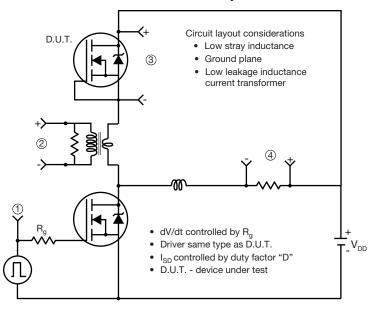


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



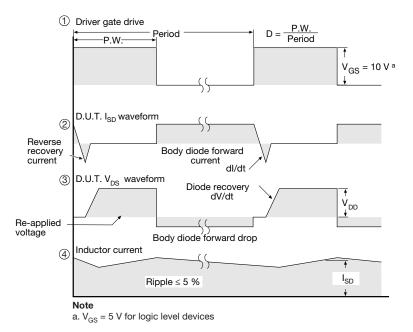


Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead





		DIMEN	ISIONS	
SYMBOL	MILLIN	IETERS	INC	HES
	MIN.	MAX.	MIN.	MAX.
А	4.30	4.70	0.169	0.185
A1	2.50	2.90	0.098	0.114
A2	2.40	2.80	0.094	0.110
b	0.60	0.80	0.024	0.031
b2	0.60	0.90	0.024	0.035
С	-	0.60	-	0.024
D	8.30	8.70	0.327	0.342
d1	14.70	15.30	0.579	0.602
d2	2.90	3.10	0.114	0.122
d3	3.30	3.70	0.130	0.146
E	9.70	10.30	0.382	0.406
е	2.50	2.70	0.098	0.106
L	13.40	13.80	0.528	0.543
L1	1.00	2.80	0.039	0.110
ØP	3.00	3.40	0.118	0.134

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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Vishay

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